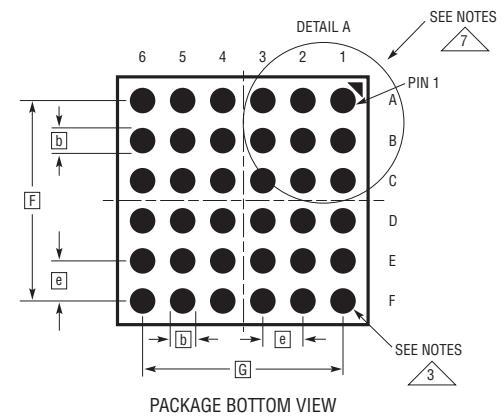
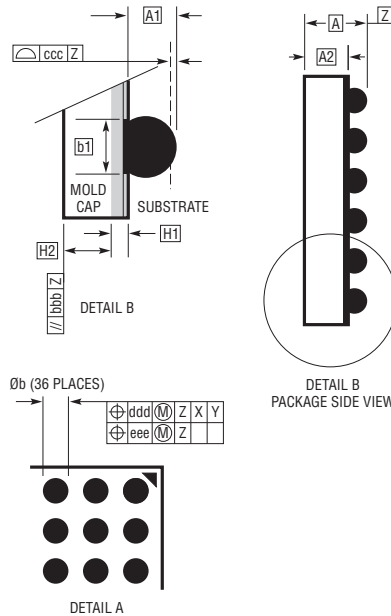
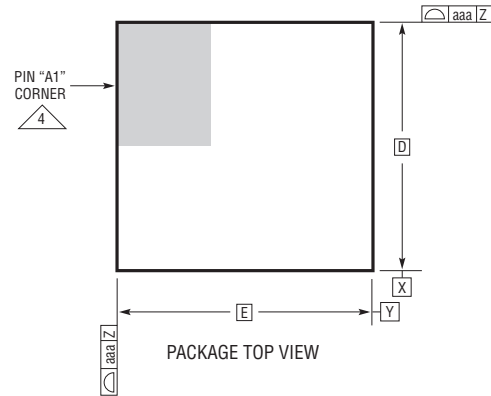
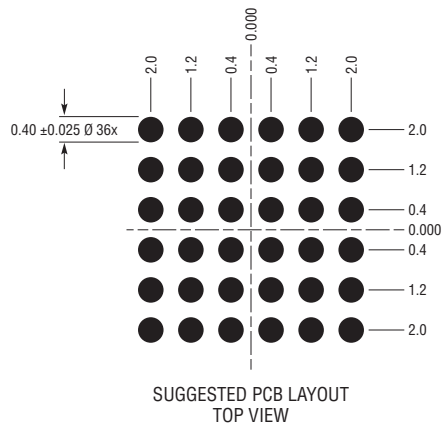


BGA Package
36-Lead (5mm × 5mm × 1.72mm)
 (Reference LTC DWG # 05-08-1671 Rev A)



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE
 - 3 BALL DESIGNATION PER JEP95
 - 4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
 - 7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.53	1.72	1.91	
A1	0.30	0.40	0.50	
A2	1.23	1.32	1.41	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		5.00		
E		5.00		
e		0.80		
F		4.00		
G		4.00		
H1	0.28	0.32	0.36	
H2	0.95	1.00	1.05	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 36				

